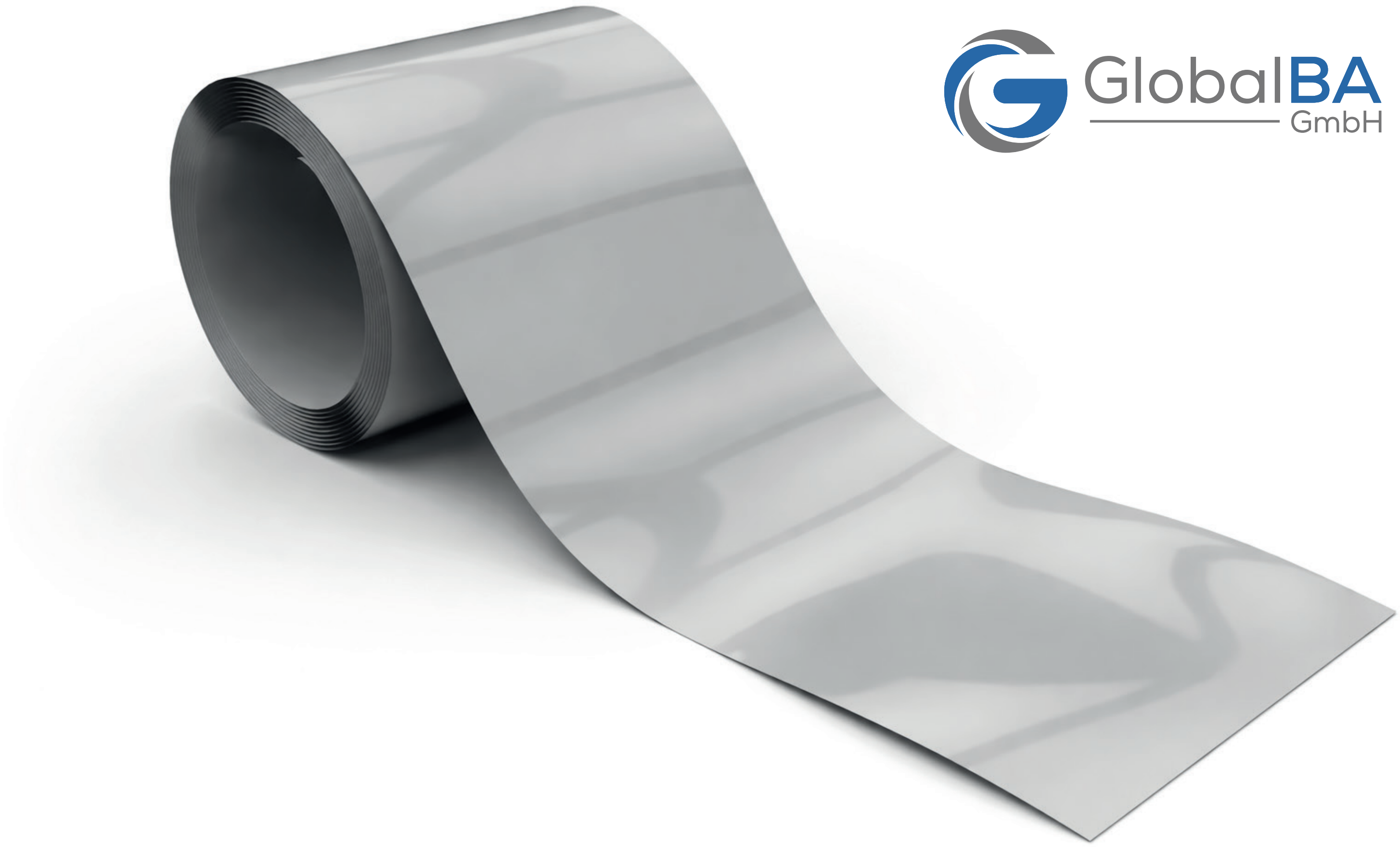


AG FILM FOR POWER ELECTRONICS

AG FILM CHARACTERISTICS

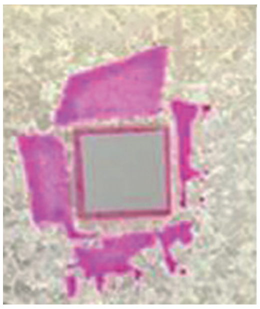
Ag sintering film	
Size (mm x mm)	100x100*
Thickness (µm) (±10%)	65
BLT** (µm) (±10%)	28
AG contents (wt.%)	> 98.0

*BLT: **B**ond **L**ine **T**hickness after sintering

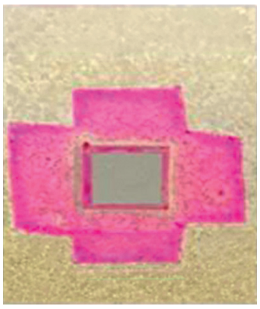
- High adhesion at low sintering pressure: 250°C, MPa, 120sec
- Fast & easy film transfer (150°C, 2~3MPa, 0.5~3sec) / No burr issue
- Min. fume during sintering

Roll

Sheet



Competitor´s Film



AMO Film

Global BA GmbH
Roentgenstr. 14
D-95478 Kemnath

☎ +49 9642 516 94 89
✉ info@globalba.de
🌐 www.globalba.de

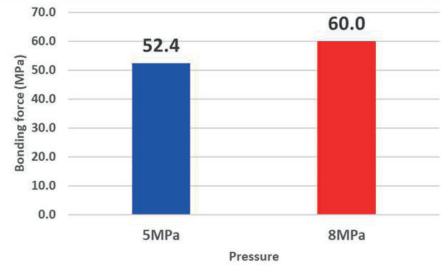
03/2026

AG FILM TRANSFER

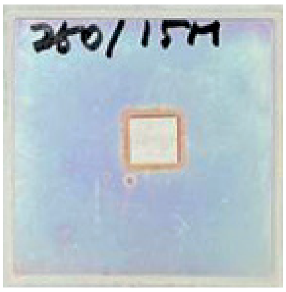
Test conditions
: PET release film (release force 8~13g/inch)
: Rubber hardness (shore A 50)
: Film transfer conditions
pressure – 2.0 MPa Temp - 150°C Time - 0.5sec

No burr after transfer

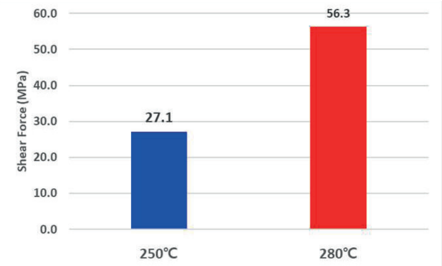
SINTERING _ AG DEPOSITED AMB SUBSTRATE



- ✓ Sintering temperature : 250°C
- ✓ Sintering time : 120 sec
- ✓ Chip surface finish : Au
- ✓ Chip size : 5*5mm



SINTERING _ BARE AMB SUBSTRATE



- ✓ Sintering conditions :
  250/280°C, 180sec, in Air
- ✓ Chip surface finish : Au
- ✓ Chip size : 5*5mm